# Power LDMOS transistor Rev. 3 — 1 September 2015

**AMPLEON** 

Product data sheet

#### **Product profile** 1.

#### 1.1 General description

A 350 W extremely rugged LDMOS power transistor for broadcast and industrial applications in the HF to 600 MHz band.

Table 1. **Application information** 

| Test signal | f         | V <sub>DS</sub> | PL  | Gp   | $\eta_D$ |
|-------------|-----------|-----------------|-----|------|----------|
|             | (MHz)     | (V)             | (W) | (dB) | (%)      |
| pulsed RF   | 108       | 50              | 350 | 28   | 75       |
| CW          | 88 to 108 | 50              | 388 | 26   | 80       |
| pulsed RF   | 30 to 512 | 50              | 400 | 15   | 48       |
| CW          | 30 to 512 | 35              | 193 | 14   | 47       |

#### 1.2 Features and benefits

- Easy power control
- Integrated ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (HF to 600 MHz)
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

#### 1.3 Applications

- Industrial, scientific and medical applications
- Broadcast transmitter applications

# 2. Pinning information

Table 2. Pinning

| Pin    | Description    | Simplified outlin | e Graphic symbol |
|--------|----------------|-------------------|------------------|
| BLF183 | XR (SOT1121A)  |                   |                  |
| 1      | drain1         |                   |                  |
| 2      | drain2         | 1 2<br>M          | 1                |
| 3      | gate1          | 5                 |                  |
| 4      | gate2          |                   | 5 5              |
| 5      | source         | [1] 3 4           | 4 7              |
|        |                |                   | <u>'</u>         |
|        |                |                   | 2<br>sym117      |
| BLF183 | XRS (SOT1121B) |                   |                  |
| 1      | drain1         | DG . DG           |                  |
| 2      | drain2         | 1 2               | 1                |
| 3      | gate1          |                   |                  |
| 4      | gate2          | 3 4 5             | 3——5             |
| 5      | source         | [1]               | 4                |
|        |                |                   | <u>"</u>         |
|        |                |                   | 2<br>sym117      |
|        |                |                   | •                |

<sup>[1]</sup> Connected to flange.

## 3. Ordering information

Table 3. Ordering information

| Type number | Packag | Package   |          |  |  |
|-------------|--------|---|----------|--|--|
|             | Name   | Description   | Version  |  |  |
| BLF183XR    | -      | flanged LDMOST ceramic package; 2 mounting holes; 4 leads | SOT1121A |  |  |
| BLF183XRS   | -      | earless flanged ceramic package; 4 leads                  | SOT1121B |  |  |

# 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter            | Conditions | Min | Max  | Unit |
|------------------|----------------------|------------|-----|------|------|
| $V_{DS}$         | drain-source voltage |            | -   | 135  | ٧    |
| $V_{GS}$         | gate-source voltage  |            | -6  | +11  | V    |
| T <sub>stg</sub> | storage temperature  |            | -65 | +150 | °C   |
| Tj               | junction temperature | [1]        | -   | 225  | °C   |

Continuous use at maximum temperature will affect the reliability, for details refer to the on-line MTF calculator.

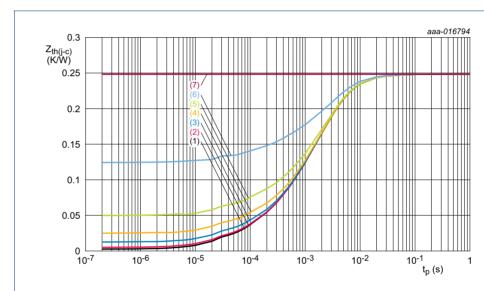
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#### 5. Thermal characteristics

Table 5. Thermal characteristics

| Symbol               | Parameter   | Conditions   |        | Тур   | Unit |
|----------------------|---|--|--------|-------|------|
| R <sub>th(j-c)</sub> | thermal resistance from junction to case          | T <sub>j</sub> = 115 °C                              | [1][2] | 0.25  | K/W  |
| Z <sub>th(j-c)</sub> | transient thermal impedance from junction to case | $T_j$ = 150 °C; $t_p$ = 100 $\mu$ s; $\delta$ = 20 % | [3]    | 0.076 | K/W  |

- [1]  $T_i$  is the junction temperature.
- [2]  $R_{th(j-c)}$  is measured under RF conditions.
- [3] See Figure 1.



- (1)  $\delta = 1 \%$
- (2)  $\delta = 2 \%$
- (3)  $\delta = 5 \%$
- (4)  $\delta = 10 \%$
- (5)  $\delta = 20 \%$
- (6)  $\delta = 50 \%$
- (7)  $\delta = 100 \% (DC)$

Fig 1. Transient thermal impedance from junction to case as a function of pulse duration

#### 6. Characteristics

#### Table 6. DC characteristics

 $T_i = 25$  °C; per section unless otherwise specified.

| Symbol              | Parameter                        | Conditions   | Min  | Тур  | Max  | Unit |
|---------------------|----------------------------------|--|------|------|------|------|
| $V_{(BR)DSS}$       | drain-source breakdown voltage   | $V_{GS} = 0 \text{ V}; I_D = 1.5 \text{ mA}$       | 135  | -    | -    | V    |
| $V_{GS(th)}$        | gate-source threshold voltage    | V <sub>DS</sub> = 10 V; I <sub>D</sub> = 150 mA    | 1.33 | 2.0  | 2.33 | V    |
| $V_{GSq}$           | gate-source quiescent voltage    | $V_{DS} = 50 \text{ V}; I_{D} = 50 \text{ mA}$     | -    | 1.9  | -    | V    |
| I <sub>DSS</sub>    | drain leakage current            | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V      | -    | -    | 1.4  | μΑ   |
| I <sub>DSX</sub>    | drain cut-off current            | $V_{GS} = V_{GS(th)} + 3.75 V;$<br>$V_{DS} = 10 V$ | -    | 21   | -    | Α    |
| I <sub>GSS</sub>    | gate leakage current             | V <sub>GS</sub> = 11 V; V <sub>DS</sub> = 0 V      | -    | -    | 140  | nA   |
| R <sub>DS(on)</sub> | drain-source on-state resistance | $V_{GS} = V_{GS(th)} + 3.75 V;$<br>$I_D = 5.25 A$  | -    | 0.29 | -    | Ω    |

#### Table 7. AC characteristics

 $T_j = 25$  °C; per section unless otherwise specified.

| Symbol           | Parameter            | Conditions   | Min | Тур | Max | Unit |
|------------------|----------------------|--|-----|-----|-----|------|
| C <sub>rs</sub>  | feedback capacitance | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz | -   | 1.1 | -   | pF   |
| C <sub>iss</sub> | input capacitance    | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz | -   | 156 | -   | pF   |
| C <sub>oss</sub> | output capacitance   | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz | -   | 51  | -   | pF   |

#### Table 8. RF characteristics

Test signal: pulsed RF;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %; f = 108 MHz; RF performance at  $V_{DS}$  = 50 V;  $I_{Dq}$  = 100 mA;  $T_{case}$  = 25 °C; unless otherwise specified; in a class-AB production test circuit.

| Symbol     | Parameter         | Conditions             | Min  | Тур | Max | Unit |
|------------|-------------------|------------------------|------|-----|-----|------|
| $G_p$      | power gain        | P <sub>L</sub> = 350 W | 26.5 | 28  | -   | dB   |
| RLin       | input return loss | P <sub>L</sub> = 350 W | -    | -10 | -7  | dB   |
| $\eta_{D}$ | drain efficiency  | P <sub>L</sub> = 350 W | 71   | 75  | -   | %    |

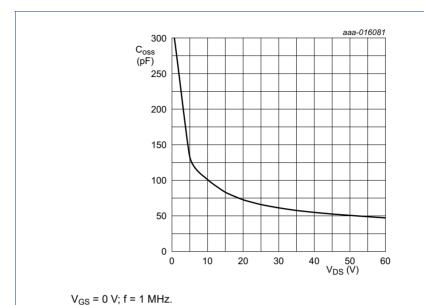


Fig 2. Output capacitance as a function of drain-source voltage; typical values per section

#### 7. Test information

#### 7.1 Ruggedness in class-AB operation

The BLF183XR and BLF183XRS are capable of withstanding a load mismatch corresponding to VSWR > 65 : 1 through all phases under the following conditions:  $V_{DS} = 50 \text{ V}$ ;  $I_{Dq} = 100 \text{ mA}$ ;  $P_L = 350 \text{ W}$  pulsed; f = 108 MHz.

#### 7.2 Impedance information

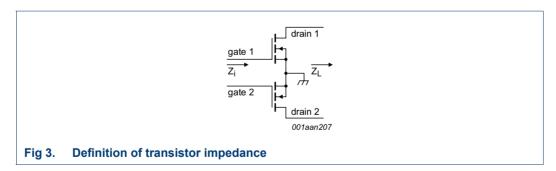


Table 9. Typical push-pull impedance

Simulated  $Z_i$  and  $Z_L$  device impedance; impedance info at  $V_{DS} = 50 \text{ V}$  and  $P_L = 350 \text{ W}$ .

| f     | Z <sub>i</sub> | Z <sub>L</sub> |
|-------|----------------|----------------|
| (MHz) | (Ω)            | (Ω)            |
| 108   | 10.3 – j35.6   | 10.9 + j2.5    |

#### 7.3 UIS avalanche energy

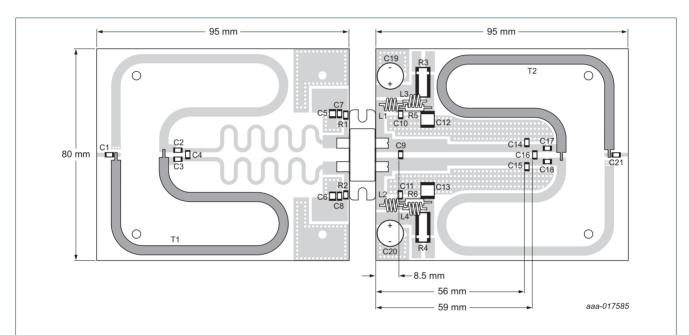
Table 10. Typical avalanche data per section

 $T_{amb} = 25$  °C; typical test data; test jig without water cooling.

| IAS  | E <sub>AS</sub> |
|------|-----------------|
| (A)  | (J)             |
| 10   | 2.6             |
| 12.5 | 1.5             |
| 15   | 1.0             |

For information see application note AN10273.

#### 7.4 Test circuit



Printed-Circuit Board (PCB): Taconic RF-35;  $\epsilon_r$  = 3.5 F/m; thickness = 0.765 mm; thickness copper plating = 35  $\mu$ m, gold plated.

See Table 11 for a list of components.

Fig 4. Component layout for class-AB production test circuit

Table 11. List of components For test circuit see Figure 4.

| Component     | Description                       | Value         | Remarks |
|---------------|-----------------------------------|---------------|---------|
| C1, C4        | multilayer ceramic chip capacitor | 51 pF [1]     |         |
| C2, C3        | multilayer ceramic chip capacitor | 150 pF [1]    |         |
| C5, C6        | multilayer ceramic chip capacitor | 4.7 μF, 50 V  |         |
| C7, C8        | multilayer ceramic chip capacitor | 820 pF [1]    |         |
| C9            | multilayer ceramic chip capacitor | 11 pF [1]     |         |
| C10, C11      | multilayer ceramic chip capacitor | 820 pF [1]    |         |
| C12, C13      | multilayer ceramic chip capacitor | 4.7 μF, 100 V |         |
| C14, C15, C21 | electrolytic capacitor            | 51 pF [1]     |         |

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 Table 11.
 List of components ...continued

For test circuit see Figure 4.

| Component      | Description                       | Value                         | Remarks                      |
|----------------|-----------------------------------|-------------------------------|------------------------------|
| C16            | multilayer ceramic chip capacitor | 7.5 pF [1]                    |                              |
| C17,C18        | multilayer ceramic chip capacitor | 120 pF [1]                    |                              |
| C19, C20       | electrolytic capacitor            | 2200 μF, 64 V                 |                              |
| L1, L2, L3, L4 | 3.0 turn 1.0 mm copper wire       | D = 3.0 mm                    |                              |
| R1, R2         | resistor                          | 510 Ω                         | SMD 1206                     |
| R3, R4         | shunt resistor                    | 0.01 Ω                        | Ohmite:<br>FC4L110R010FER    |
| R5, R6         | metal film resistor               | 10 Ω, 0.6 W                   | SMD 1206                     |
| T1, T2         | semi rigid coax                   | $50 \Omega$ , length = 160 mm | EZ Form:<br>EZ-141-AL-TP-M17 |

<sup>[1]</sup> American Technical Ceramics type 100B or capacitor of same quality.

#### 7.5 Graphical data

The following figures are measured in a class-AB production test circuit.

#### 7.5.1 1-Tone CW pulsed

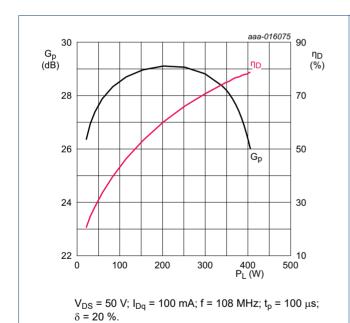
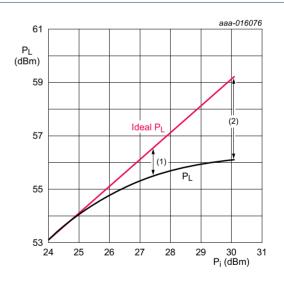


Fig 5. Power gain and drain efficiency as function of output power; typical values

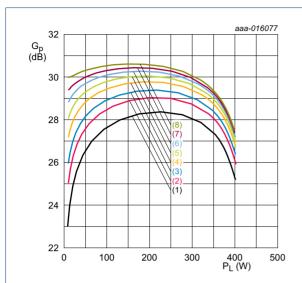


 $V_{DS}$  = 50 V;  $I_{Dq}$  = 100 mA; f = 108 MHz;  $t_p$  = 100  $\mu s$ ;  $\delta$  = 20 %.

- (1)  $P_{L(1dB)} = 55.5 \text{ dBm } (354 \text{ W})$
- (2)  $P_{L(3dB)} = 56.1 \text{ dBm } (404 \text{ W})$

Fig 6. Output power as a function of input power; typical values

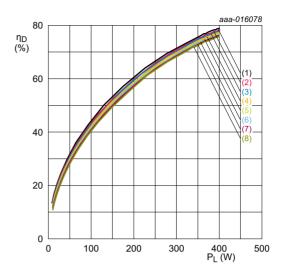
**Power LDMOS transistor** 



 $V_{DS}$  = 50 V; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $I_{Dq} = 20 \text{ mA}$
- (2)  $I_{Dq} = 100 \text{ mA}$
- (3)  $I_{Dq} = 200 \text{ mA}$
- (4)  $I_{Dq} = 400 \text{ mA}$
- (5)  $I_{Dq} = 600 \text{ mA}$
- (6)  $I_{Dq} = 800 \text{ mA}$
- (7)  $I_{Dq} = 1000 \text{ mA}$
- (8)  $I_{Dq} = 1200 \text{ mA}$

Fig 7. Power gain as a function of output power; typical values

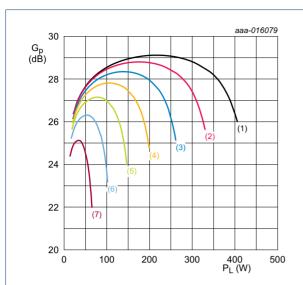


 $V_{DS}$  = 50 V; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $I_{Dq} = 20 \text{ mA}$
- (2)  $I_{Dq} = 100 \text{ mA}$
- (3)  $I_{Dq} = 200 \text{ mA}$
- (4)  $I_{Dq} = 400 \text{ mA}$
- (5)  $I_{Dq} = 600 \text{ mA}$
- (6)  $I_{Dq} = 800 \text{ mA}$
- (7)  $I_{Dq} = 1000 \text{ mA}$
- (8)  $I_{Dq} = 1200 \text{ mA}$

Fig 8. Drain efficiency as a function of output power; typical values

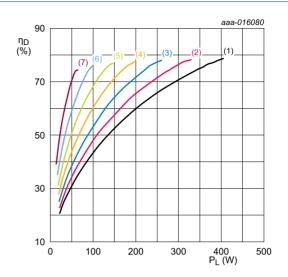
**Power LDMOS transistor** 



 $I_{Dq}$  = 100 mA; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $V_{DS} = 50 \text{ V}$
- (2)  $V_{DS} = 45 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$
- (4)  $V_{DS} = 35 \text{ V}$
- (5)  $V_{DS} = 30 \text{ V}$
- (6)  $V_{DS} = 25 \text{ V}$
- (7)  $V_{DS} = 20 \text{ V}$

Fig 9. Power gain as a function of output power; typical values



 $I_{Dq}$  = 100 mA; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $V_{DS} = 50 \text{ V}$
- (2)  $V_{DS} = 45 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$
- (4)  $V_{DS} = 35 \text{ V}$
- (5)  $V_{DS} = 30 \text{ V}$ (6)  $V_{DS} = 25 V$
- (7)  $V_{DS} = 20 \text{ V}$

Fig 10. Drain efficiency as a function of output power; typical values

## 8. Package outline

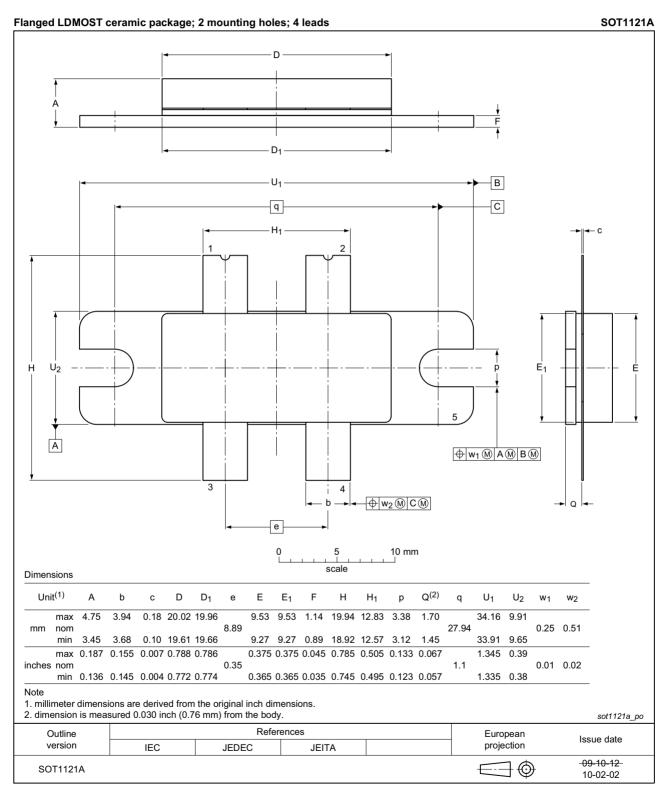


Fig 11. Package outline SOT1121A

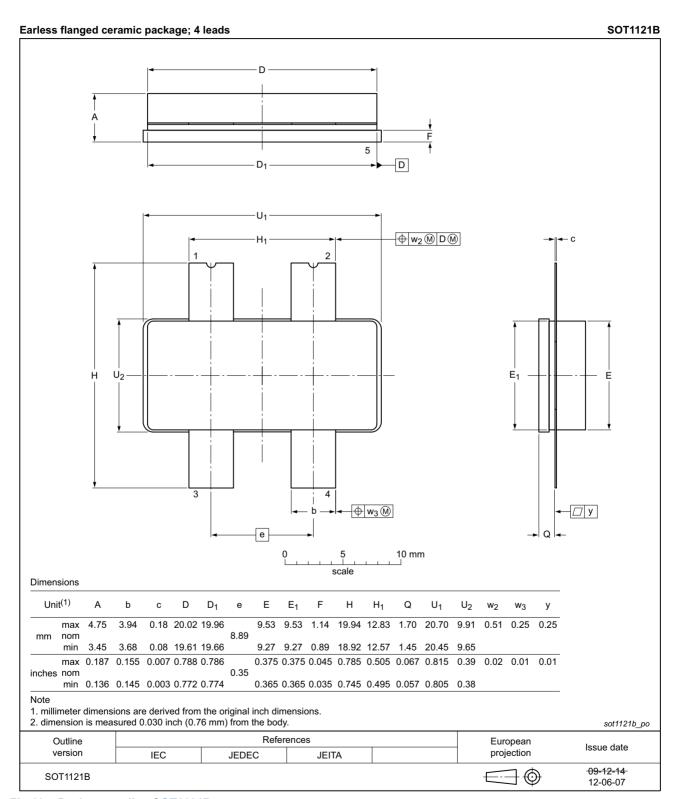


Fig 12. Package outline SOT1121B

## 9. Handling information

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

#### 10. Abbreviations

Table 12. Abbreviations

| Acronym | Description   |
|---------|---|
| CW      | Continuous Wave   |
| ESD     | ElectroStatic Discharge                                 |
| HF      | High Frequency  |
| LDMOS   | Laterally Diffused Metal-Oxide Semiconductor            |
| LDMOST  | Laterally Diffused Metal-Oxide Semiconductor Transistor |
| MTF     | Median Time to Failure                                  |
| SMD     | Surface Mounted Device                                  |
| UIS     | Unclamped Inductive Switching                           |
| VSWR    | Voltage Standing-Wave Ratio                             |

# 11. Revision history

Table 13. Revision history

| Document ID            | Release date   | Data sheet status    | Change notice | Supersedes             |  |
|------------------------|--|----------------------|---------------|------------------------|--|
| BLF183XR_BLF183XRS#3   | 20150901   | Product data sheet   | -             | BLF183XR_BLF183XRS v.2 |  |
| Modifications:         | <ul> <li>The format of this document has been redesigned to comply with the new identity guidelines of Ampleon.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> </ul> |                      |               |                        |  |
| BLF183XR_BLF183XRS v.2 | 20150522   | Product data sheet   | -             | BLF183XR_BLF183XRS v.1 |  |
| BLF183XR_BLF183XRS v.1 | 20140819   | Objective data sheet | -             | -                      |  |

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| Document status[1][2]          | Product status[3] | Definition  |
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# **AMPLEON**

# BLF183XR; BLF183XRS

**Power LDMOS transistor** 

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